

| DTS $\square-6 \square \square-\square$-V SPECIFICATION |  |  |  | $\begin{gathered} \hline \text { FILE NO. } \\ \text { REV. } \\ \text { Page. } \\ \hline \end{gathered}$ |  |  |
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| 1. Style <br> This specification describes "TACTILE SWITCH", mainly used as signal switch of electric devices, with the general requirements of mechanical and electrical characteristic. <br> 1.1 Operating Temperature Range: $-25^{\circ} \mathrm{C}+70^{\circ} \mathrm{C}$ <br> 1.2 Storage Temperature Range : $-30^{\circ} \mathrm{C}+80^{\circ} \mathrm{C}$ <br> 2. Current Range: $50 \mathrm{~mA}, 12 \mathrm{VDC}$ <br> 3.Type of Actuation: Tactile feedback <br> 4.Test Sequence: |  |  |  |  |  |  |
|  | ITEM | DESCRIPTION | TEST CONDITIONS | REQU | MENT |  |
|  | 1 | Visual Examination | By visual examination check without any out pressure \& testing. | There shal defects th serviceabilty product. | no |  |
|  | 2 | Contact Resistance | Applying a static load 1.5~2 times the operating force to the center made with a 1 kHz small current contact resistance meter. | $100 \mathrm{~m} \Omega$ Max. |  |  |
|  | 3 | Insulation Resistance | Measurements shall be made following application of 500 V DC potential across terminals and cover for 1 minute $\pm 5$ seconds. | 100M 2 Min. |  |  |
|  | 4 | Dielectric Withstanding Voltage | $250 \mathrm{~V} \mathrm{AC}(50 \mathrm{~Hz}$ or 60 Hz$)$ shall be applied across terminals and cover for 1 minute | There shall be no breakdown or flashover. |  |  |
|  | 5 | Capacitance | $1 \mathrm{MHz} \pm 10 \mathrm{kHz}$ | 5 pF max. |  |  |
|  | 6. | Bounce | 3 to 4 operations at a rate of 15 m seconds Max. cycles per second |  |  |  |


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|  | 7. | Operating Force | Applied in the direction of operation. | OF |  |  |  |  |  |
|  |  |  |  | K | N | R | S |  |  |
|  |  |  |  | $\begin{aligned} & 100 \pm 50 \\ & {[98 N+499]} \end{aligned}$ | $\left.\begin{array}{c} 160 \pm 50 \\ [1.508) \geq 49 N] \end{array}\right]$ | $\left\|\begin{array}{c} 260 \pm 50 \\ 25588) \pm 49 \mathrm{~V} \end{array}\right\|$ | $\begin{gathered} 320 \pm 80 \\ B 3.1360 \pm 78 A N \end{gathered}$ |  |  |
|  | 8. | Stroke | Placing the switch such that the direction of switch operation is vertical and then gradually increasing the load applied to the stem, the stroke distance for the stem to come to a stop shall be measured. | $0.25+0.2 /-0.1 \mathrm{~mm}$ |  |  |  |  |  |
|  | 9. | Stop Strength | Placing the switch such that the direction of switch operation is vertical, a static load of $3 \mathrm{kgf}(29.4 \mathrm{~N})$ shall be applied in the direction of stem operation for a period of 15 seconds | (1)As shown in item 4~7 <br> (2) Contact Resistance: 200m $\Omega$ Max <br> (3) Insulation Resistance: $10 \mathrm{M} \Omega \mathrm{Min}$ |  |  |  |  |  |
|  | 10. | Solder Heat Resistance | -Through Hole Type <br> (1)Soldering Temperature:260 $\pm 5^{\circ} \mathrm{C}$ <br> (2)Duration of Solder Immersion: $5 \pm 1$ seconds. <br> (3) Frequency of Soldering Process 2 times max. (PCB is 1.6 mm in thickness) SMT Type ~DTSM Series(4/4) | (1)Shall be free from pronounced backlash and falling-off or breakage terminals <br> (2)As shown in item 4, 5 <br> (Contact Resistance: <br> $200 \mathrm{~m} \Omega$ Max <br> ( Insulation Resistance: <br> $10 \mathrm{M} \Omega \mathrm{Min}$ |  |  |  |  |  |
|  | 11. | Vibration | Shall be vibrated in accordance with <br> Method 201A of MIL-STD-202F <br> (Frequency: $10-55-10 \mathrm{~Hz}$ in <br> 1-min/cycle. <br> (Direction: 3 vertical <br> $\quad$ directions including the <br> directions of operation <br> (Test time: 2 hours each <br> $\quad$ direction. <br> (Swing distance $=1.5 \mathrm{~mm}$ | (1)As shown in item 4~7 <br> (Contact Resistance: <br> $200 \mathrm{~m} \Omega$ Max <br> (Insulation Resistance: $10 \mathrm{M} \Omega \mathrm{Min}$ |  |  |  |  |  |


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|  | 12 | Shock | Shall be shocked in accordance with Method 213B condition A of MIL-STD-202F <br> 1)Acceleration; 50G <br> 2)Action time: $11 \pm 1 \mathrm{~m}$ seconds <br> 3)Testing Direction: 6 sides <br> 4)Test Cycle: 3 times in each direction | 1)As shown in item 4~7 <br> 2)Contact Resistance: $200 \mathrm{~m} \Omega$ Max <br> 3)Insulation Resistance: $10 \mathrm{M} \Omega \mathrm{Min}$ |
|  | 13 | Solder ability | Through Hole Soldering 1)Temperature : $245 \pm 3{ }^{\circ} \mathrm{C}$ Lead-Free solder: M705E JIS Z 3282 A (Tin $96.5 \%$, Silver $3 \%$, Copper $0.5 \%$ ) 2)Flux: $5 \sim 10$ sec 3)Duration of solder Immersion $: 5 \pm 1 \mathrm{sec}$ | No anti-soldering and the coverage of dipping into solder must more than 66\% was requested. |
| $\begin{aligned} & \frac{\succsim}{\underline{1}} \\ & \frac{\bar{m}}{\stackrel{1}{2}} \\ & \frac{1}{2} \end{aligned}$ | 14 | Operating Life | Measurements shall be made following the test forth below: <br> 1) $5 \mathrm{~mA}, 5 \mathrm{VDC}$ resistive load <br> 2)Applying a static load the operating force to the center of the stem in the direction of operation <br> 3)Cycle of Operation: <br> (Through Hole , S.M.T <br> Dome=Phosphor Bronze) 200,000 cycle's Min. For 100,160gf 100,000 cycle's Min. For 260gf 50,000 cycle's Min. For 320,520gf (S.M.T Dome=Stainless Steel) 1,000,000 cycle's Min~100,160gf 500,000 cycle's Min~260gf 300,000 cycle's Min~320 , 520gf | 1)As shown in item 4, 5 <br> 2)Operating force: $\pm 50 \%$ of initial force. <br> 3)Contact Resistance: $10 \Omega$ Max <br> 4)Insulation Resistance: 10M $\Omega$ Min <br> 5)Bounce: 10 m seconds Max |
|  | 15 | $\begin{aligned} & \text { Resistance } \\ & \text { Low } \\ & \text { Temperature } \end{aligned}$ | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: <br> 1) Temperature: $-25 \pm 3^{\circ} \mathrm{C}$ <br> 2)Time:96 hours | 1)As shown in item 4~7 <br> 2)Contact Resistance: 200m $\Omega$ Max <br> 3)Insulation Resistance: 10M $\Omega$ Min |
|  | 16 | $\begin{gathered} \text { Resistance } \\ \text { High } \\ \text { Temperature } \end{gathered}$ | Following the test set forth below the sample shall be left in normal temperature and humidity conditions for an hour before the measurements are made: <br> 1)Temperature: $80 \pm 2^{\circ} \mathrm{C}$ <br> 2)Time:96 hours | 1)As shown in item 4~7 <br> 2)Contact Resistance: 200m $\Omega$ Max <br> 3)Insulation Resistance: 10M $\Omega$ Min |


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| 17 | Resistance Humidity | Following the test set forth below | 1)As shown in item 4~7 <br> 2)Contact Resistance: $200 \mathrm{~m} \Omega$ Max <br> 3)Insulation Resistance: $10 \mathrm{M} \Omega \mathrm{Min}$ |  |  |
|  |  | temperature and humidity <br> conditions for an hour before the |  |  |  |
|  |  | measurements are made: <br> 1) Temperature: $40 \pm 2^{\circ} \mathrm{C}$ <br> 2)Relative Humidity:90~95\% <br> 3)Time:96 hours |  |  |  |

5. SOLDERING CONDITIONS:

- Condition for Reflow Soldering - S.M.T Series


■ The condition mentioned above is the temperature on the Cu foil of the PCB surface. There are cases where board's temperature greatly differs from switch's surface be used not to allow switch's surface temperature to exceed $260^{\circ} \mathrm{C}$.

- Manual Soldering

| Soldering Temperature | Max. $350^{\circ} \mathrm{C}$ |
| :--- | :---: |
| Continuous Soldering Time | Max. 5 seconds |

- Precautions in Handling

1. Care should be exercised so that flux from the upper part of the printed circuit board does not adhere to the switch.
2. Except for washable type do not wash the switch body.
3. 
4. Please make sure that there is no flux rose over the surface of the PCB


| ITEM | DESC | Q'TY | MATERIALS | TREATMENT | REMARK |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 1. | COVER | 1 | STAINLESS STEEL | NONE | - |
| 2. | STEM | 1 | HIGH - TEMP <br> THERMOPLASTIC <br> NYLON UL 94V-0 | $\rightarrow$ | - |
| 3. | CONTACT | 1 | PHOSPHOR <br> BRONZE | WITH SILVER <br> CLADDING | - |
| 4. | TERMINAL | 1 | BRASS | WITH SILVER <br> PLATING | - |
| 5. | BASE | 1 | HIGH - TEMP <br> THERMOPLASTIC <br> NYLON UL 94V-0 | MOLDED BLACK | - |
| 6. | CAP | 1 | THERMOPLASTIC <br> ABS | $\rightarrow$ | - |

Remark:

K = With Cap

$\qquad$
$\qquad$
 V L Soldering: $\mathrm{V}=$ Lead Free

Dimension H :
$1=4.3 \mathrm{~mm}$
$2=5.0 \mathrm{~mm}$
$3=7.0 \mathrm{~mm}$
$44(48)=7.3 \mathrm{~mm}$
$5=9.5 \mathrm{~mm}$
$6=13 \mathrm{~mm}$
Prod. No. : D T S

